

## 74VHC74 Dual D-Type Flip-Flop with Preset and Clear

### Features

- High Speed:  $f_{MAX} = 170\text{MHz}$  (typ.) at  $T_A = 25^\circ\text{C}$
- High noise immunity:  $V_{NIH} = V_{NIL} = 28\% V_{CC}$  (min.)
- Power down protection is provided on all inputs
- Low power dissipation:  $I_{CC} = 2\mu\text{A}$  (max.) at  $T_A = 25^\circ\text{C}$
- Pin and function compatible with 74HC74

### General Description


The VHC74 is an advanced high speed CMOS Dual D-Type Flip-Flop fabricated with silicon gate CMOS technology. It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. The signal level applied to the D input is transferred to the Q output during the positive going transition of the CK pulse.  $\overline{\text{CLR}}$  and  $\overline{\text{PR}}$  are independent of the CK and are accomplished by setting the appropriate input LOW.

An input protection circuit ensures that 0V to 7V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5V to 3V systems and two supply systems such as battery backup. This circuit prevents device destruction due to mismatched supply and input voltages.

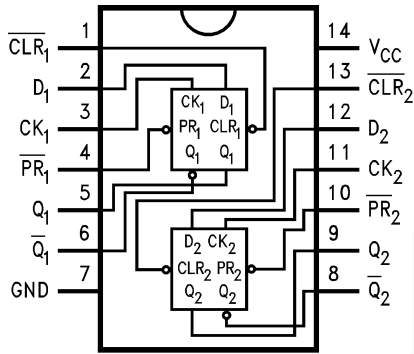
### Ordering Information

Order Number	Package Number	Package Description
74VHC74M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74VHC74SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHC74MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74VHC74N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

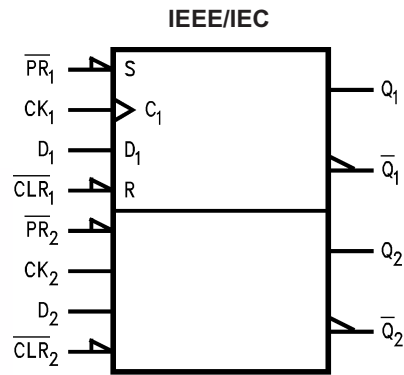
Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

 All packages are lead free per JEDEC: J-STD-020B standard.

### Connection Diagram



### Logic Symbol



### Pin Description

Pin Names	Description
D <sub>1</sub> , D <sub>2</sub>	Data Inputs
CK <sub>1</sub> , CK <sub>2</sub>	Clock Pulse Inputs
$\overline{\text{CLR}}_1$ , $\overline{\text{CLR}}_2$	Direct Clear Inputs
$\overline{\text{PR}}_1$ , $\overline{\text{PR}}_2$	Direct Preset Inputs
Q <sub>1</sub> , $\overline{\text{Q}}_1$ , Q <sub>2</sub> , $\overline{\text{Q}}_2$	Output

### Truth Table

Inputs				Outputs		Function
$\overline{\text{CLR}}$	$\overline{\text{PR}}$	D	CK	Q	$\overline{\text{Q}}$	
L	H	X	X	L	H	Clear
H	L	X	X	H	L	Preset
L	L	X	X	H <sup>(1)</sup>	H <sup>(1)</sup>	
H	H	L	$\nearrow$	L	H	
H	H	H	$\nearrow$	H	L	
H	H	X	$\curvearrowright$	Q <sub>n</sub>	Q <sub>n</sub>	No Change

**Note:**

1. This configuration is nonstable; that is, it will not persist when preset and clear inputs return to their inactive (HIGH) state.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
$V_{CC}$	Supply Voltage	-0.5V to +7.0V
$V_{IN}$	DC Input Voltage	-0.5V to +7.0V
$V_{OUT}$	DC Output Voltage	-0.5V to $V_{CC} + 0.5V$
$I_{IK}$	Input Diode Current	-20mA
$I_{OK}$	Output Diode Current	$\pm 20mA$
$I_{OUT}$	DC Output Current	$\pm 25mA$
$I_{CC}$	DC $V_{CC}/GND$ Current	$\pm 50mA$
$T_{STG}$	Storage Temperature	-65°C to +150°C
$T_L$	Lead Temperature (Soldering, 10 seconds)	260°C

## Recommended Operating Conditions<sup>(2)</sup>

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
$V_{CC}$	Supply Voltage	2.0V to +5.5V
$V_{IN}$	Input Voltage	0V to +5.5V
$V_{OUT}$	Output Voltage	0V to $V_{CC}$
$T_{OPR}$	Operating Temperature	-40°C to +85°C
$t_r, t_f$	Input Rise and Fall Time, $V_{CC} = 3.3V \pm 0.3V$ $V_{CC} = 5.0V \pm 0.5V$	0ns/V ~ 100ns/V 0ns/V ~ 20ns/V

### Note:

- Unused inputs must be held HIGH or LOW. They may not float.

## DC Electrical Characteristics

Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to +85°C		Units			
				Min.	Typ.	Max.	Min.	Max.				
V <sub>IH</sub>	HIGH Level Input Voltage	2.0		1.50			1.50		V			
		3.0–5.5		0.7 × V <sub>CC</sub>			0.7 × V <sub>CC</sub>					
V <sub>IL</sub>	LOW Level Input Voltage	2.0				0.50		0.50	V			
		3.0–5.5				0.3 × V <sub>CC</sub>		0.3 × V <sub>CC</sub>				
V <sub>OH</sub>	HIGH Level Output Voltage	2.0	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -50μA	1.9	2.0		1.9		V		
		3.0			2.9	3.0		2.9				
		4.5			4.4	4.5		4.4				
		3.0				I <sub>OH</sub> = -4mA	2.58				2.48	
		4.5				I <sub>OH</sub> = -8mA	3.94				3.80	
V <sub>OL</sub>	LOW Level Output Voltage	2.0	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 50μA		0.0	0.1		0.1	V		
		3.0				0.0	0.1		0.1			
		4.5				0.0	0.1		0.1			
		3.0				I <sub>OL</sub> = 4mA			0.36			0.44
		4.5				I <sub>OL</sub> = 8mA			0.36			0.44
I <sub>IN</sub>	Input Leakage Current	0–5.5	V <sub>IN</sub> = 5.5V or GND			±0.1		±1.0	μA			
I <sub>CC</sub>	Quiescent Supply Current	5.5	V <sub>IN</sub> = V <sub>CC</sub> or GND			2.0		20.0	μA			

## AC Electrical Characteristics

Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to +85°C		Units
				Min.	Typ.	Max.	Min.	Max.	
f <sub>MAX</sub>	Maximum Clock Frequency	3.3 ± 0.3	C <sub>L</sub> = 15pF	80	125		70		MHz
			C <sub>L</sub> = 50pF	50	75		45		
		5.0 ± 0.5	C <sub>L</sub> = 15pF	130	170		110		
			C <sub>L</sub> = 50pF	90	115		75		
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay Time (CK-Q, $\bar{Q}$ )	3.3 ± 0.3	C <sub>L</sub> = 15pF		6.7	11.9	1.0	14.0	ns
			C <sub>L</sub> = 50pF		9.2	15.4	1.0	17.5	
		5.0 ± 0.5	C <sub>L</sub> = 15pF		4.6	7.3	1.0	8.5	
			C <sub>L</sub> = 50pF		6.1	9.3	1.0	10.5	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay Time ( $\bar{CLR}$ , $\bar{PR}$ -Q, $\bar{Q}$ )	3.3 ± 0.3	C <sub>L</sub> = 15pF		7.6	12.3	1.0	14.5	ns
			C <sub>L</sub> = 50pF		10.1	15.8	1.0	18.0	
		5.0 ± 0.5	C <sub>L</sub> = 15pF		4.8	7.7	1.0	9.0	
			C <sub>L</sub> = 50pF		6.3	9.7	1.0	11.0	
C <sub>IN</sub>	Input Capacitance		V <sub>CC</sub> = Open		4	10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance		( <sup>3</sup> )		25				pF

## Note:

3. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained from the equation:

$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 2 \text{ (per F/F).}$$

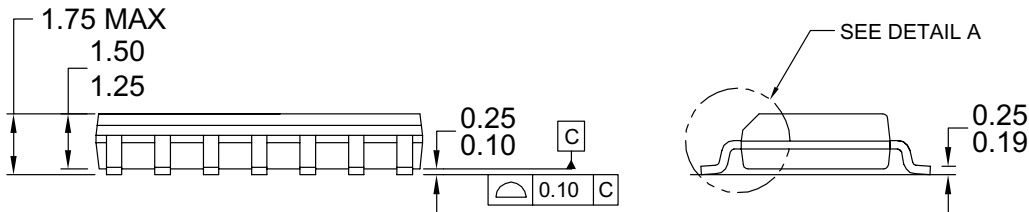
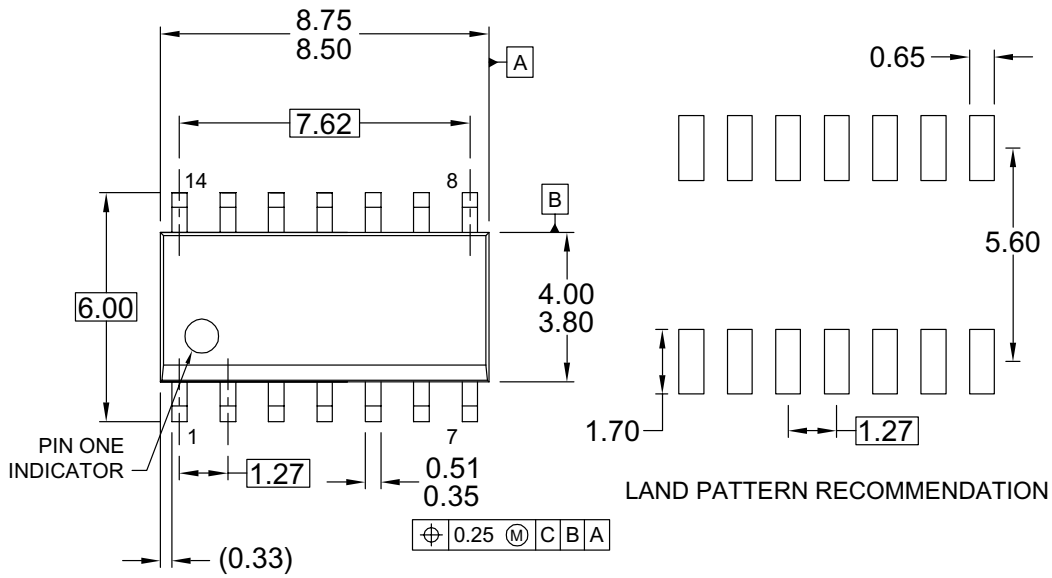
## AC Operating Requirements

Symbol	Parameter	V <sub>CC</sub> (V) <sup>(4)</sup>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40°C to +85°C		Units
			Typ.	Guaranteed Minimum			
t <sub>W(L)</sub> , t <sub>W(H)</sub>	Minimum Pulse Width (CK)	3.3		6.0	7.0	ns	
		5.0		5.0	5.0		
t <sub>W(L)</sub>	Minimum Pulse Width ( $\bar{CLR}$ , $\bar{PR}$ )	3.3		6.0	7.0	ns	
		5.0		5.0	5.0		
t <sub>S</sub>	Minimum Setup Time	3.3		6.0	7.0	ns	
		5.0		5.0	5.0		
t <sub>H</sub>	Minimum Hold Time	3.3		0.5	0.5	ns	
		5.0		0.5	0.5		
t <sub>REC</sub>	Minimum Recovery Time ( $\bar{CLR}$ , $\bar{PR}$ )	3.3		5.0	5.0	ns	
		5.0		3.0	3.0		

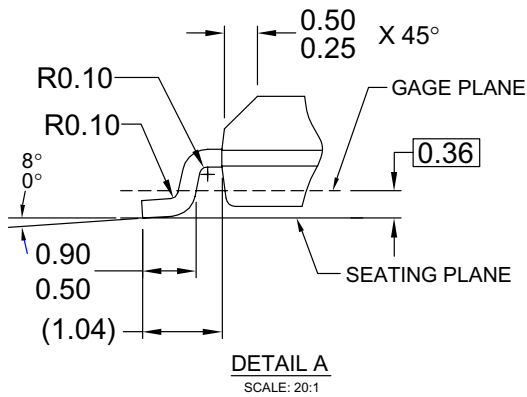
## Note:

4. V<sub>CC</sub> is 3.3 ± 0.3V or 5.0 ± 0.5V

### Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED



- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

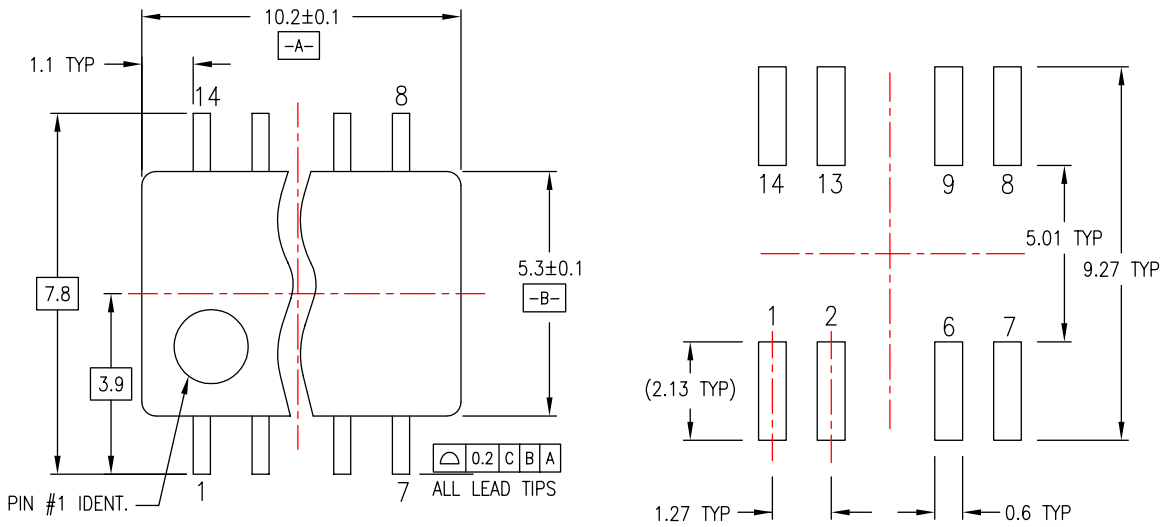
**Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow**

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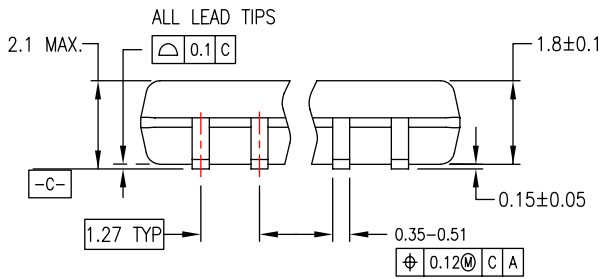
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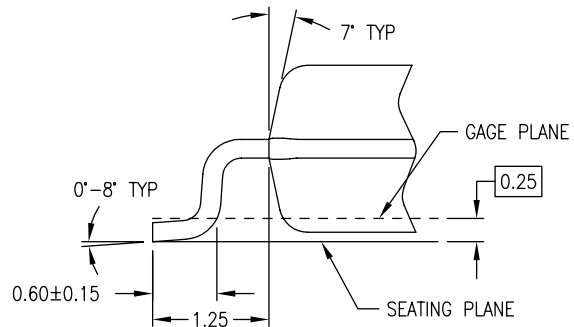
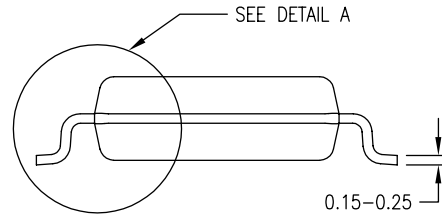
Physical Dimensions (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DREVC

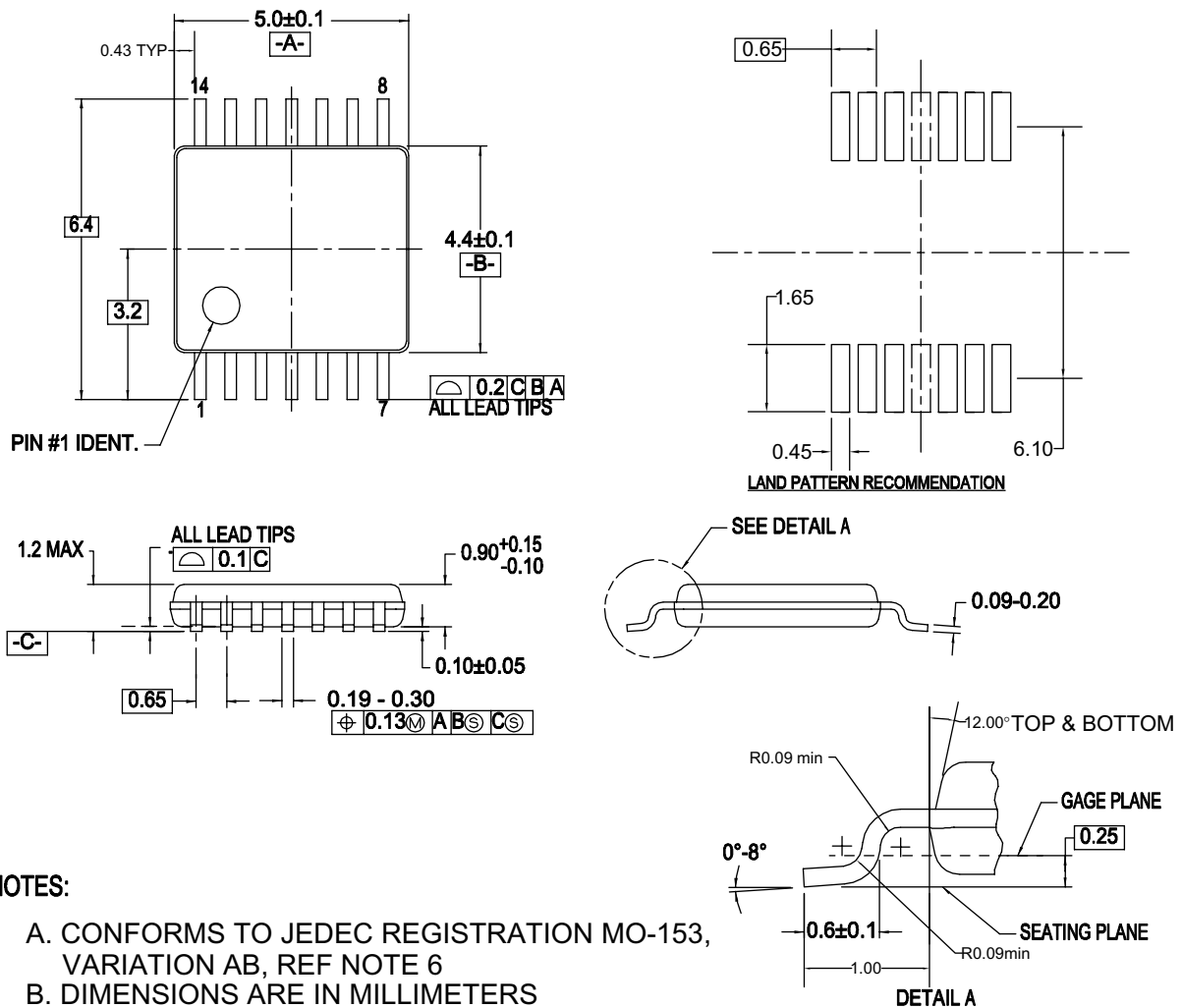
Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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**Physical Dimensions** (Continued)



**NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

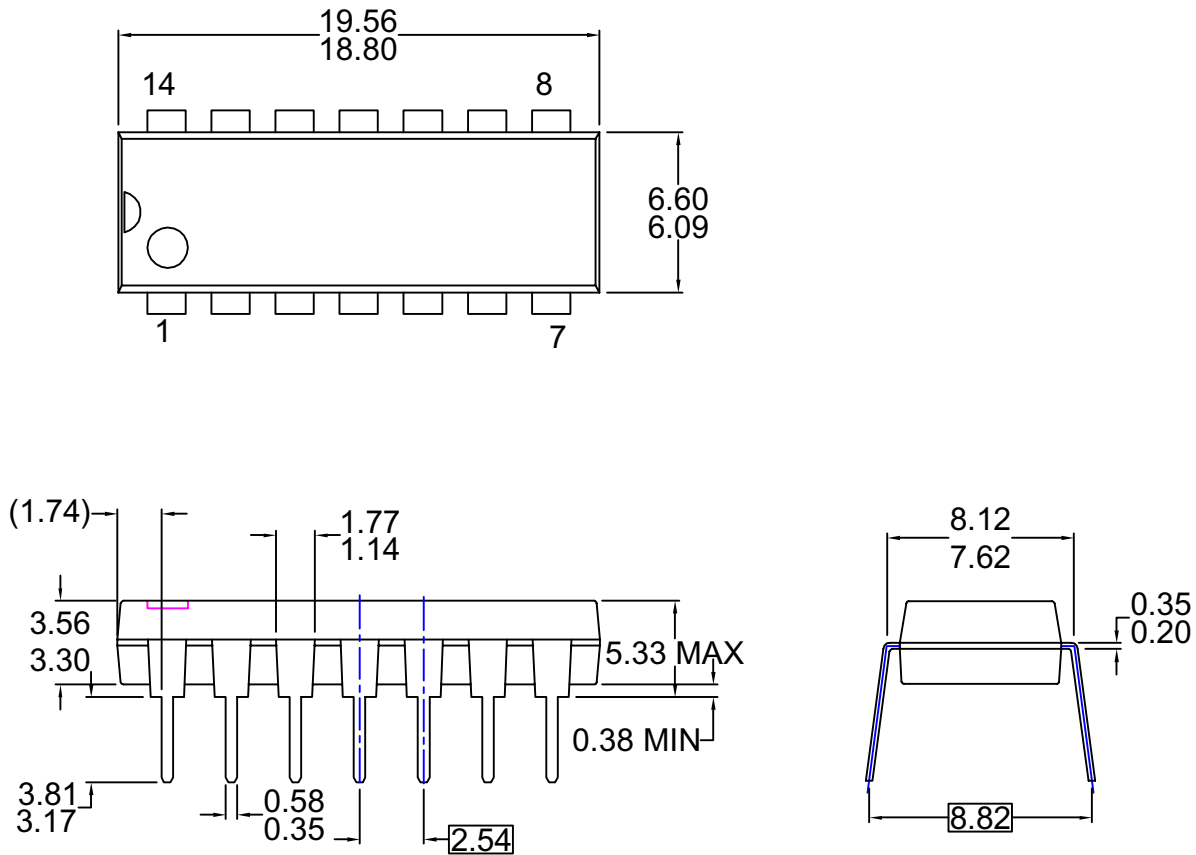
**Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide**

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**Physical Dimensions** (Continued)

- NOTES: UNLESS OTHERWISE SPECIFIED**
- THIS PACKAGE CONFORMS TO**
- A) JEDEC MS-001 VARIATION BA
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
  - D) DIMENSIONS AND TOLERANCES PER ASME Y14.5-1994
  - E) DRAWING FILE NAME: MKT-N14AREV7

**Figure 4. 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide**

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

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Datasheet Identification	Product Status	Definition
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